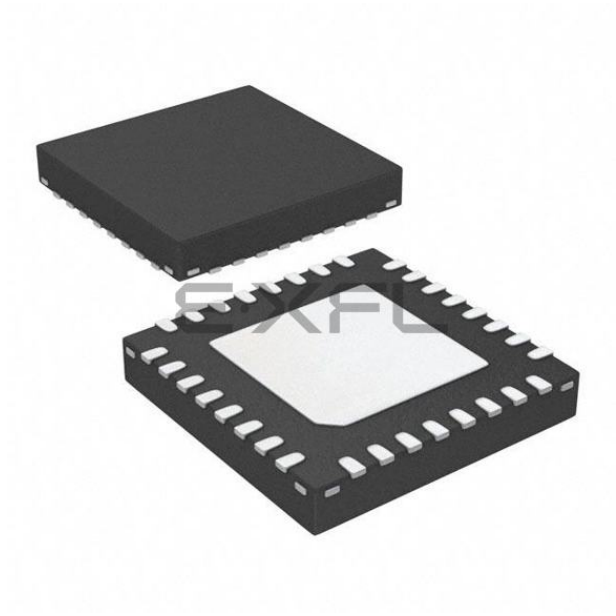
Infineon Technologies - MB95F636KWQN-G-SNE1 Datasheet



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What is "Embedded - Microcontrollers"?

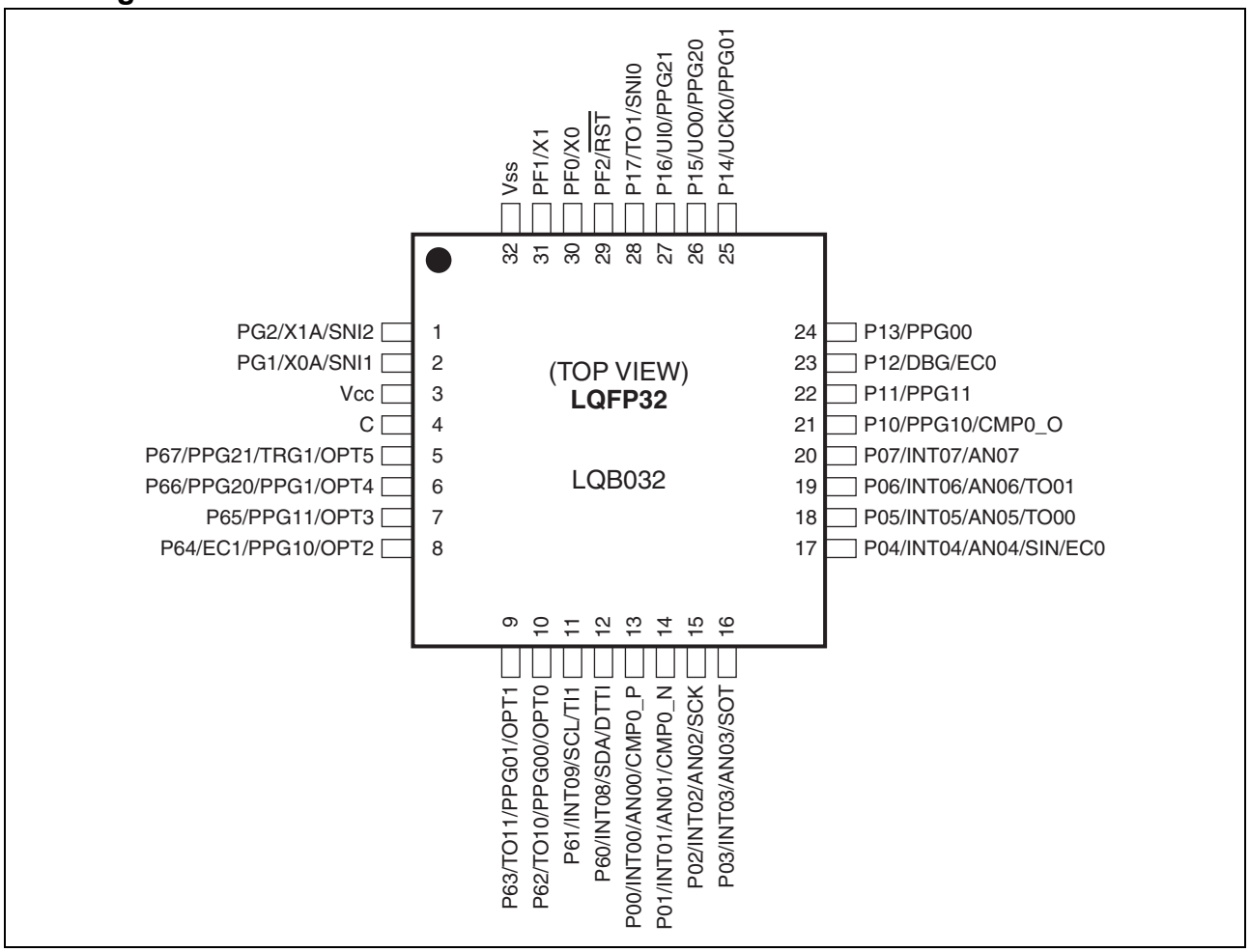
"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

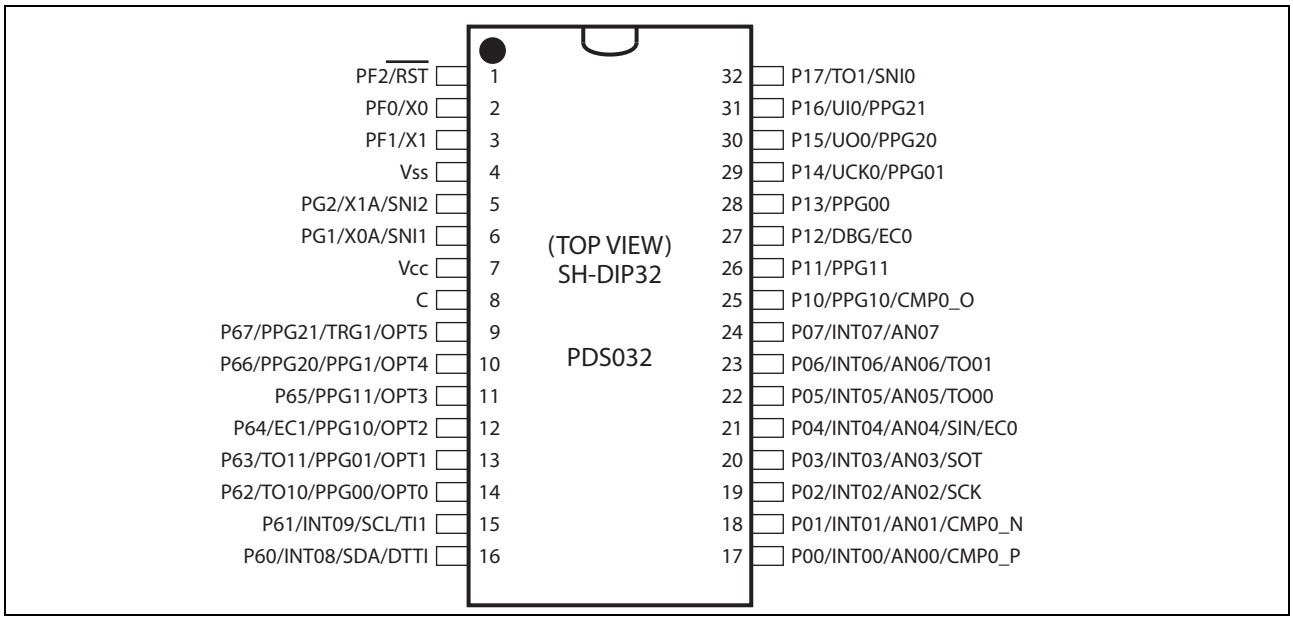
Applications of "Embedded - Microcontrollers"

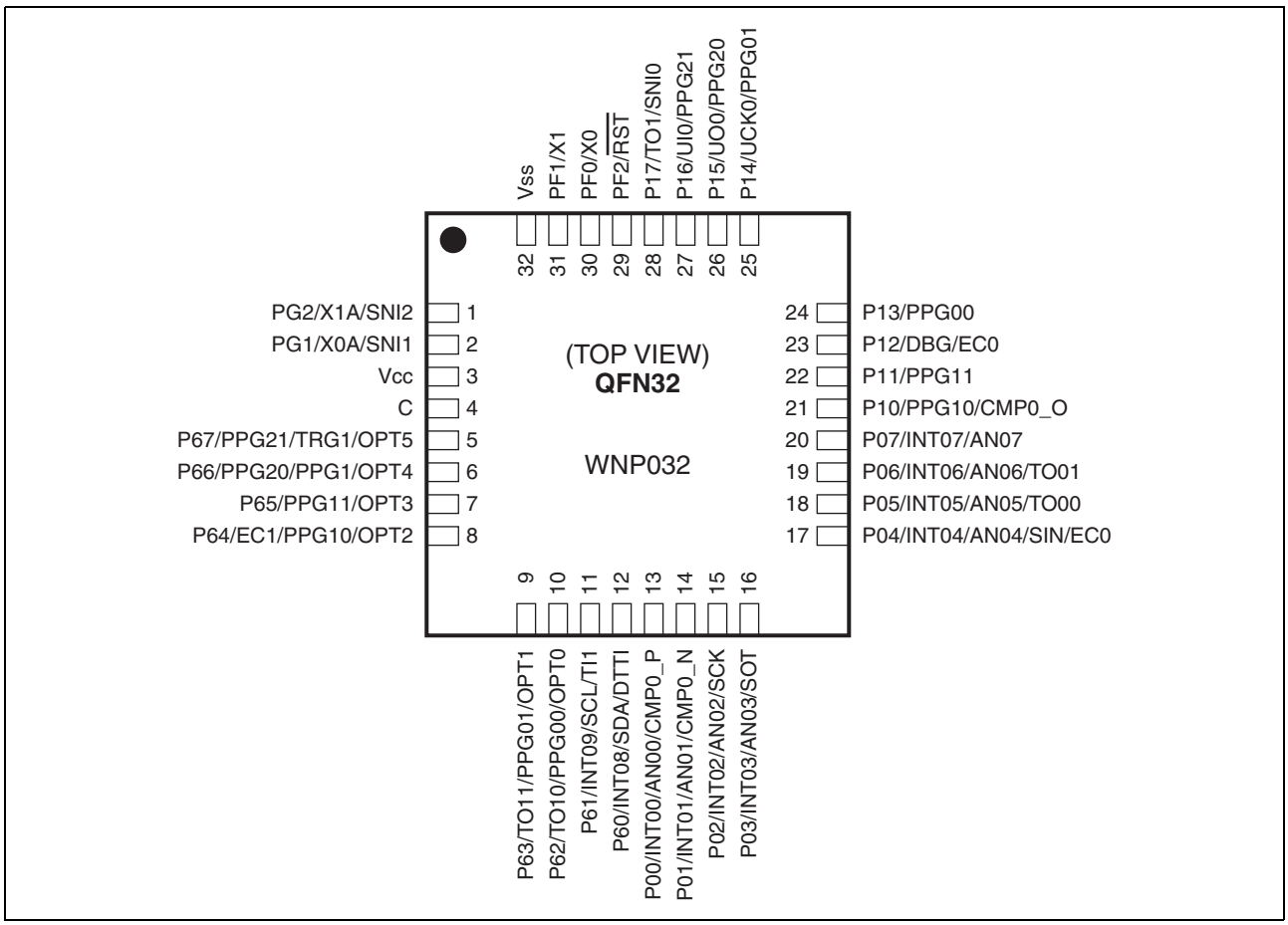
Details	
Product Status	Obsolete
Core Processor	F²MC-8FX
Core Size	8-Bit
Speed	16MHz
Connectivity	I²C, LINbus, SIO, UART/USART
Peripherals	LVD, POR, PWM, WDT
Number of I/O	29
Program Memory Size	36KB (36K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	1K x 8
Voltage - Supply (Vcc/Vdd)	2.4V ~ 5.5V
Data Converters	A/D 8x8/10b
Oscillator Type	External
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	32-WQFN Exposed Pad
Supplier Device Package	32-QFN (5x5)
Purchase URL	https://www.e-xfl.com/product-detail/infineon-technologies/mb95f636kwqn-g-sne1

The on-chip debug function requires that Vcc, Vss and one serial wire be connected to an evaluation tool. For details of the connection method, refer to “CHAPTER 25 EXAMPLE OF SERIAL PROGRAMMING CONNECTION” in “New 8FX MB95630H Series Hardware Manual”.

4. Pin Assignment




PF2/RST 1
PF0/X0 2
PF1/X1 3
Vss 4
PG2/X1A/SNI2 5
PG1/X0A/SNI1 6
Vcc 7
C 8
P67/PPG21/TRG1/OPT5 9
P66/PPG20/PPG1/OPT4 10
P65/PPG11/OPT3 11
P64/EC1/PPG10/OPT2 12
P63/TO11/PPG01/OPT1 13
P62/TO10/PPG00/OPT0 14
P61/INT09/SCL/TI1 15
P60/INT08/SDA/DTTI 16
(TOP VIEW)
SH-DIP32
PDS032
32 P17/TO1/SNI0
31 P16/UI0/PPG21
30 P15/UO0/PPG20
29 P14/UCK0/PPG01
28 P13/PPG00
27 P12/DBG/EC0
26 P11/PPG11
25 P10/PPG10/CMP0_O
24 P07/INT07/AN07
23 P06/INT06/AN06/TO01
22 P05/INT05/AN05/TO00
21 P04/INT04/AN04/SIN/EC0
20 P03/INT03/AN03/SOT
19 P02/INT02/AN02/SCK
18 P01/INT01/AN01/CMP0_N
17 P00/INT00/AN00/CMP0_P


Vss 32
PF1/X1 31
PF0/X0 30
PF2/RST 29
P17/TO1/SNI0 28
P16/UI0/PPG21 27
P15/UO0/PPG20 26
P14/UCK0/PPG01 25
PG2/X1A/SNI2 1
PG1/X0A/SNI1 2
Vcc 3
C 4
P67/PPG21/TRG1/OPT5 5
P66/PPG20/PPG1/OPT4 6
P65/PPG11/OPT3 7
P64/EC1/PPG10/OPT2 8
(TOP VIEW)
QFN32
WNP032
24 P13/PPG00
23 P12/DBG/EC0
22 P11/PPG11
21 P10/PPG10/CMP0_O
20 P07/INT07/AN07
19 P06/INT06/AN06/TO01
18 P05/INT05/AN05/TO00
17 P04/INT04/AN04/SIN/EC0
9 P63/TO11/PPG01/OPT1
10 P62/TO10/PPG00/OPT0
11 P61/INT09/SCL/TI1
12 P60/INT08/SDA/DTTI
13 P00/INT00/AN00/CMP0_P
14 P01/INT01/AN01/CMP0_N
15 P02/INT02/AN02/SCK
16 P03/INT03/AN03/SOT

7.3 Precautions for Use Environment

Reliability of semiconductor devices depends on ambient temperature and other conditions as described above.

For reliable performance, do the following:

(1) Humidity

Prolonged use in high humidity can lead to leakage in devices as well as printed circuit boards. If high humidity levels are anticipated, consider anti-humidity processing.

(2) Discharge of Static Electricity

When high-voltage charges exist close to semiconductor devices, discharges can cause abnormal operation. In such cases, use anti-static measures or processing to prevent discharges.

(3) Corrosive Gases, Dust, or Oil

Exposure to corrosive gases or contact with dust or oil may lead to chemical reactions that will adversely affect the device. If you use devices in such conditions, consider ways to prevent such exposure or to protect the devices.

(4) Radiation, Including Cosmic Radiation

Most devices are not designed for environments involving exposure to radiation or cosmic radiation. Users should provide shielding as appropriate.

(5) Smoke, Flame

CAUTION: Plastic molded devices are flammable, and therefore should not be used near combustible substances. If devices begin to smoke or burn, there is danger of the release of toxic gases.

Customers considering the use of Cypress products in other special environmental conditions should consult with sales representatives.

8. Notes On Device Handling

- Preventing latch-ups
  When using the device, ensure that the voltage applied does not exceed the maximum voltage rating.
  In a CMOS IC, if a voltage higher than V_{CC} or a voltage lower than V_{SS} is applied to an input/output pin that is neither a medium-withstand voltage pin nor a high-withstand voltage pin, or if a voltage out of the rating range of power supply voltage mentioned in “18.1 Absolute Maximum Ratings” of “Electrical Characteristics” is applied to the V_{CC} pin or the V_{SS} pin, a latch-up may occur.
  When a latch-up occurs, power supply current increases significantly, which may cause a component to be thermally destroyed.

- Stabilizing supply voltage
  Supply voltage must be stabilized.
  A malfunction may occur when power supply voltage fluctuates rapidly even though the fluctuation is within the guaranteed operating range of the V_{CC} power supply voltage.
  As a rule of voltage stabilization, suppress voltage fluctuation so that the fluctuation in V_{CC} ripple (p-p value) at the commercial frequency (50 Hz/60 Hz) does not exceed 10% of the standard V_{CC} value, and the transient fluctuation rate does not exceed 0.1 V/ms at a momentary fluctuation such as switching the power supply.

- Notes on using the external clock
  When an external clock is used, oscillation stabilization wait time is required for power-on reset, wake-up from sub-clock mode or stop mode.

Address	Register abbreviation	Register name	R/W	Initial value
0x0F80	WRARH0	Wild register address setting register (upper) ch. 0	R/W	0b00000000
0x0F81	WRARL0	Wild register address setting register (lower) ch. 0	R/W	0b00000000
0x0F82	WRDR0	Wild register data setting register ch. 0	R/W	0b00000000
0x0F83	WRARH1	Wild register address setting register (upper) ch. 1	R/W	0b00000000
0x0F84	WRARL1	Wild register address setting register (lower) ch. 1	R/W	0b00000000
0x0F85	WRDR1	Wild register data setting register ch. 1	R/W	0b00000000
0x0F86	WRARH2	Wild register address setting register (upper) ch. 2	R/W	0b00000000
0x0F87	WRARL2	Wild register address setting register (lower) ch. 2	R/W	0b00000000
0x0F88	WRDR2	Wild register data setting register ch. 2	R/W	0b00000000
0x0F89 to 0x0F91	—	(Disabled)	—	—
0x0F92	T01CR0	8/16-bit composite timer 01 status control register 0	R/W	0b00000000
0x0F93	T00CR0	8/16-bit composite timer 00 status control register 0	R/W	0b00000000
0x0F94	T01DR	8/16-bit composite timer 01 data register	R/W	0b00000000
0x0F95	T00DR	8/16-bit composite timer 00 data register	R/W	0b00000000
0x0F96	TMCR0	8/16-bit composite timer 00/01 timer mode control register	R/W	0b00000000
0x0F97	T11CR0	8/16-bit composite timer 11 status control register 0	R/W	0b00000000
0x0F98	T10CR0	8/16-bit composite timer 10 status control register 0	R/W	0b00000000
0x0F99	T11DR	8/16-bit composite timer 11 data register	R/W	0b00000000
0x0F9A	T10DR	8/16-bit composite timer 10 data register	R/W	0b00000000
0x0F9B	TMCR1	8/16-bit composite timer 10/11 timer mode control register	R/W	0b00000000
0x0F9C	PPS01	8/16-bit PPG01 cycle setting buffer register	R/W	0b11111111
0x0F9D	PPS00	8/16-bit PPG00 cycle setting buffer register	R/W	0b11111111
0x0F9E	PDS01	8/16-bit PPG01 duty setting buffer register	R/W	0b11111111
0x0F9F	PDS00	8/16-bit PPG00 duty setting buffer register	R/W	0b11111111
0x0FA0	PPS11	8/16-bit PPG11 cycle setting buffer register	R/W	0b11111111
0x0FA1	PPS10	8/16-bit PPG10 cycle setting buffer register	R/W	0b11111111
0x0FA2	PDS11	8/16-bit PPG11 duty setting buffer register	R/W	0b11111111
0x0FA3	PDS10	8/16-bit PPG10 duty setting buffer register	R/W	0b11111111
0x0FA4	PPGS	8/16-bit PPG start register	R/W	0b00000000
0x0FA5	REVC	8/16-bit PPG output inversion register	R/W	0b00000000
0x0FA6	PPS21	8/16-bit PPG21 cycle setting buffer register	R/W	0b11111111
0x0FA7	PPS20	8/16-bit PPG20 cycle setting buffer register	R/W	0b11111111

Address	Register abbreviation	Register name	R/W	Initial value
0x0FCE	OPDBRH5	16-bit MPG output data buffer register (upper) ch. 5	R/W	0b00000000
0x0FCF	OPDBRL5	16-bit MPG output data buffer register (lower) ch. 5	R/W	0b00000000
0x0FD0	OPDBRH6	16-bit MPG output data buffer register (upper) ch. 6	R/W	0b00000000
0x0FD1	OPDBRL6	16-bit MPG output data buffer register (lower) ch. 6	R/W	0b00000000
0x0FD2	OPDBRH7	16-bit MPG output data buffer register (upper) ch. 7	R/W	0b00000000
0x0FD3	OPDBRL7	16-bit MPG output data buffer register (lower) ch. 7	R/W	0b00000000
0x0FD4	OPDBRH8	16-bit MPG output data buffer register (upper) ch. 8	R/W	0b00000000
0x0FD5	OPDBRL8	16-bit MPG output data buffer register (lower) ch. 8	R/W	0b00000000
0x0FD6	OPDBRH9	16-bit MPG output data buffer register (upper) ch. 9	R/W	0b00000000
0x0FD7	OPDBRL9	16-bit MPG output data buffer register (lower) ch. 9	R/W	0b00000000
0x0FD8	OPDBRHA	16-bit MPG output data buffer register (upper) ch. A	R/W	0b00000000
0x0FD9	OPDBRLA	16-bit MPG output data buffer register (lower) ch. A	R/W	0b00000000
0x0FDA	OPDBRHB	16-bit MPG output data buffer register (upper) ch. B	R/W	0b00000000
0x0FDB	OPDBRLB	16-bit MPG output data buffer register (lower) ch. B	R/W	0b00000000
0x0FDC	OPDUR	16-bit MPG output data register (upper)	R	0b0000XXXX
0x0FDD	OPDLR	16-bit MPG output data register (lower)	R	0bXXXXXXXX
0x0FDE	CPCUR	16-bit MPG compare clear register (upper)	R/W	0bXXXXXXXX
0x0FDF	CPCLR	16-bit MPG compare clear register (lower)	R/W	0bXXXXXXXX
0x0FE0, 0x0FE1	—	(Disabled)	—	—
0x0FE2	TMBUR	16-bit MPG timer buffer register (upper)	R	0bXXXXXXXX
0x0FE3	TMBLR	16-bit MPG timer buffer register (lower)	R	0bXXXXXXXX
0x0FE4	CRTH	Main CR clock trimming register (upper)	R/W	0b000XXXXX
0x0FE5	CRTL	Main CR clock trimming register (lower)	R/W	0b000XXXXX
0x0FE6	—	(Disabled)	—	—
0x0FE7	CRTDA	Main CR clock temperature dependent adjustment register	R/W	0b000XXXXX
0x0FE8	SYSC	System configuration register	R/W	0b11000011
0x0FE9	CMCR	Clock monitoring control register	R/W	0b00000000
0x0FEA	CMDR	Clock monitoring data register	R	0b00000000
0x0FEB	WDTH	Watchdog timer selection ID register (upper)	R	0bXXXXXXXX
0x0FEC	WDTL	Watchdog timer selection ID register (lower)	R	0bXXXXXXXX
0x0FED, 0x0FEE	—	(Disabled)	—	—
0x0FEF	WICR	Interrupt pin selection circuit control register	R/W	0b01000000
0x0FF0 to 0x0FFF	—	(Disabled)	—	—

15.1 Port 0

Port 0 is a general-purpose I/O port. This section focuses on its functions as a general-purpose I/O port. For details of peripheral functions, refer to their respective chapters in “New 8FX MB95630H Series Hardware Manual”.

15.1.1 Port 0 configuration

Port 0 is made up of the following elements.

- General-purpose I/O pins/peripheral function I/O pins
- Port 0 data register (PDR0)
- Port 0 direction register (DDR0)
- Port 0 pull-up register (PUL0)
- A/D input disable register (lower) (AIDRL)

15.1.2 Block diagrams of port 0

- P00/INT00/AN00/CMP0_P pin

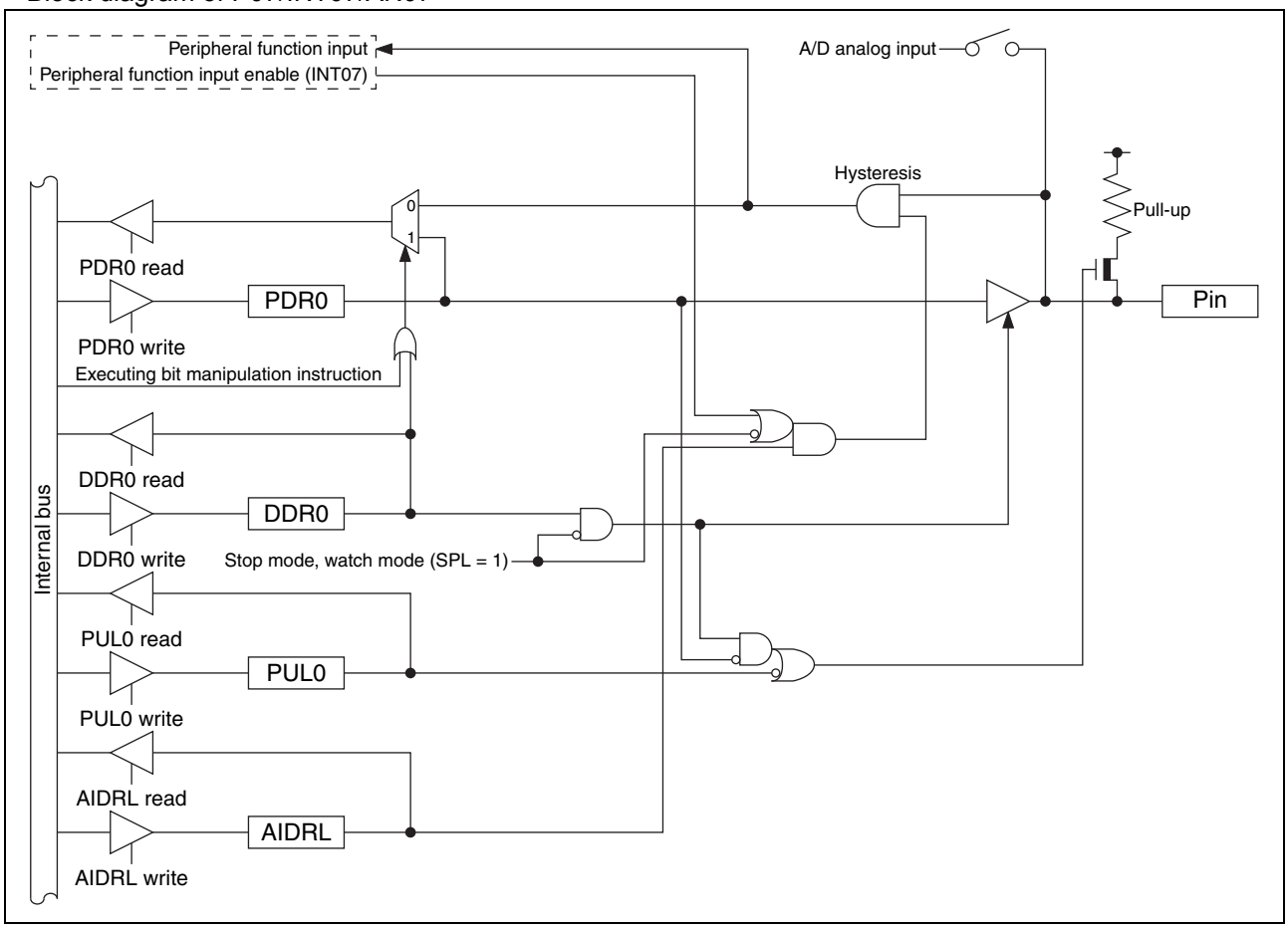
  This pin has the following peripheral functions:
  - External interrupt circuit input pin (INT00)
  - 8/10-bit A/D converter analog input pin (AN00)
  - Comparator non-inverting analog input (positive input) pin (CMP0_P)

- P01/INT01/AN01/CMP0_N pin

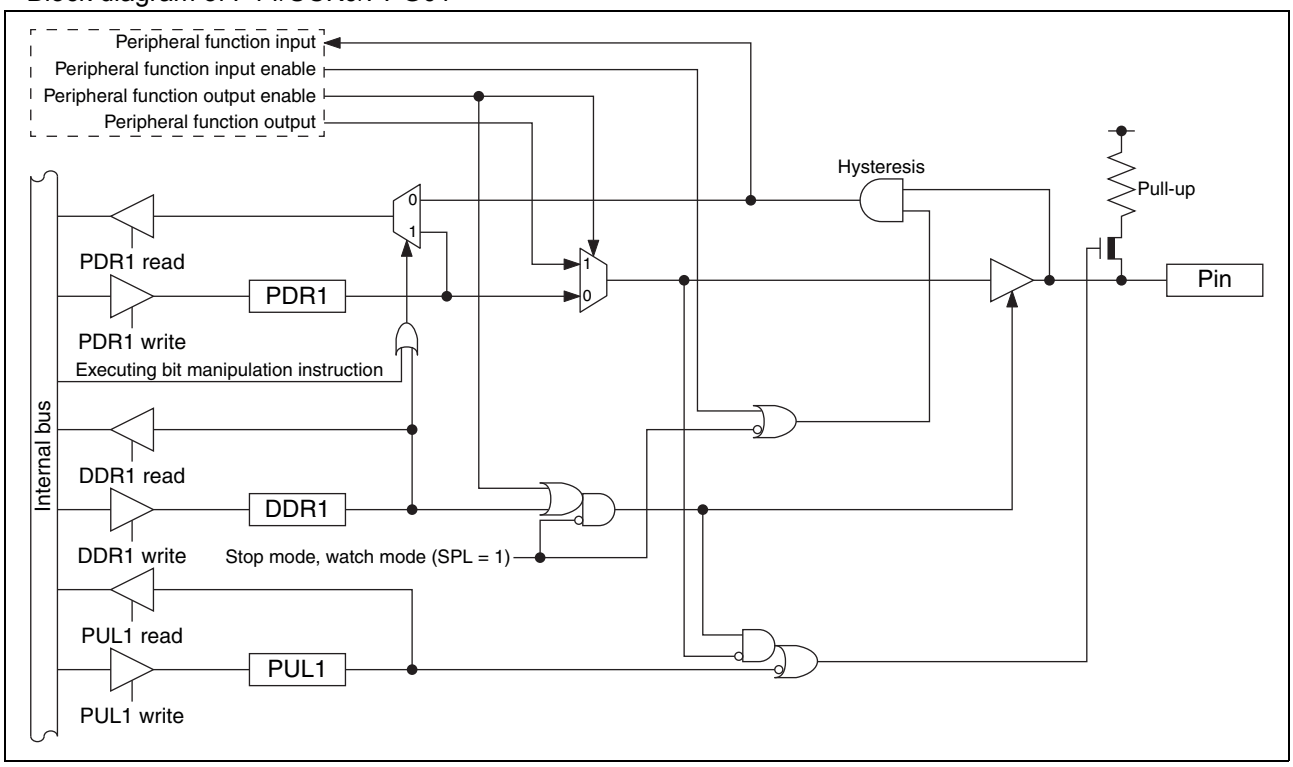
  This pin has the following peripheral functions:
  - External interrupt circuit input pin (INT01)
  - 8/10-bit A/D converter analog input pin (AN01)
  - Comparator inverting analog input (negative input) pin (CMP0_N)

- P07/INT07/AN07 pin
  This pin has the following peripheral functions:
  - External interrupt circuit input pin (INT07)
  - 8/10-bit A/D converter analog input pin (AN07)

- Block diagram of P07/INT07/AN07



- Block diagram of P14/UCK0/PPG01



15.2.3 Port 1 registers

- Port 1 register functions

Register abbreviation	Data	Read	Read by read-modify-write (RMW) instruction	Write
PDR1	0	Pin state is “L” level.	PDR1 value is “0”.	As output port, outputs “L” level.
	1	Pin state is “H” level.	PDR1 value is “1”.	As output port, outputs “H” level.*
DDR1	0	Port input enabled		
	1	Port output enabled		
PUL1	0	Pull-up disabled		
	1	Pull-up enabled		

*: If the pin is an N-ch open drain pin, the pin state becomes Hi-Z.

- Correspondence between registers and pins for port 1

	Correspondence between related register bits and pins							
Pin name	P17	P16	P15	P14	P13	P12	P11	P10
PDR1	bit7	bit6	bit5	bit4	bit3	bit2*	bit1	bit0
DDR1								
PUL1								

*: Though P12 has no pull-up function, bit2 in the PUL1 register can still be accessed. The operation of P12 is not affected by the setting of bit2 in the PUL1 register.

15.2.4 Port 1 operations

- Operation as an output port
  - A pin becomes an output port if the bit in the DDR1 register corresponding to that pin is set to “1”.
  - For a pin shared with other peripheral functions, disable the output of such peripheral functions.
  - When a pin is used as an output port, it outputs the value of the PDR1 register to external pins.
  - If data is written to the PDR1 register, the value is stored in the output latch and is output to the pin set as an output port as it is.
  - Reading the PDR1 register returns the PDR1 register value.

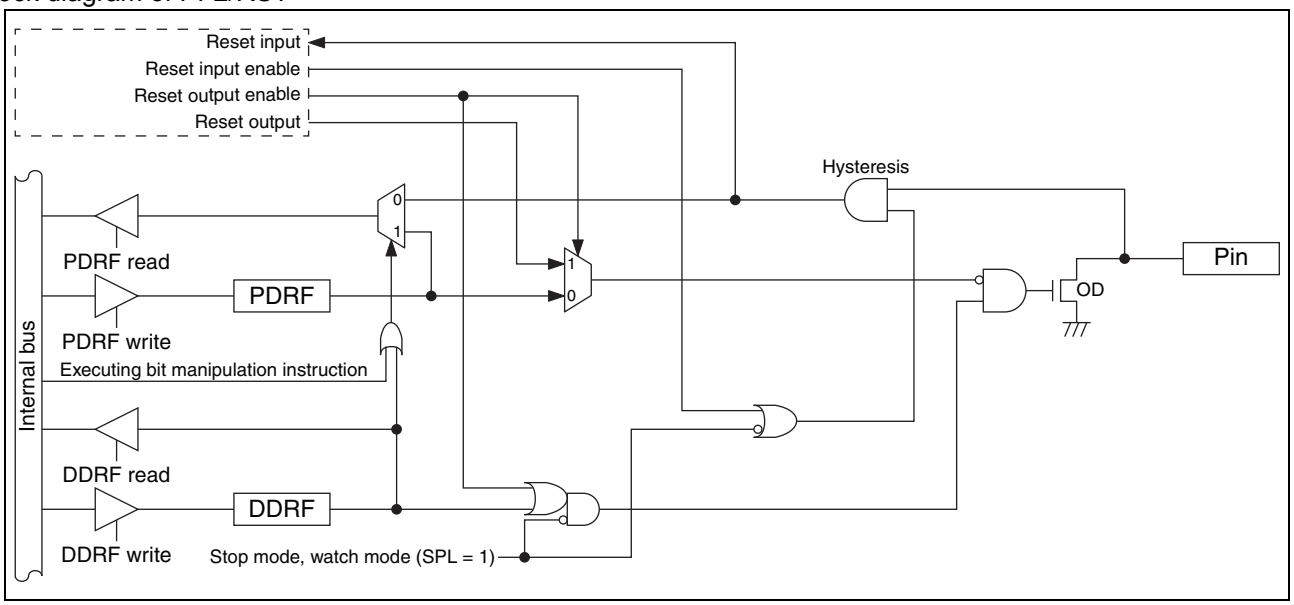
- Operation as an input port
  - A pin becomes an input port if the bit in the DDR1 register corresponding to that pin is set to “0”.
  - For a pin shared with other peripheral functions, disable the output of such peripheral functions.
  - If data is written to the PDR1 register, the value is stored in the output latch but is not output to the pin set as an input port.
  - Reading the PDR1 register returns the pin value. However, if the read-modify-write (RMW) type of instruction is used to read the PDR1 register, the PDR1 register value is returned.

- Operation as a peripheral function output pin
  - A pin becomes a peripheral function output pin if the peripheral output function is enabled by setting the output enable bit of a peripheral function corresponding to that pin.
  - The pin value can be read from the PDR1 register even if the peripheral function output is enabled. Therefore, the output value of a peripheral function can be read by the read operation on the PDR1 register. However, if the read-modify-write (RMW) type of instruction is used to read the PDR1 register, the PDR1 register value is returned.

- Operation as a peripheral function input pin
  - To set a pin as an input port, set the bit in the DDR1 register corresponding to the input pin of a peripheral function

- PF2/$\overline{\text{RST}}$ pin
  This pin has the following peripheral function:
  - Reset pin ($\overline{\text{RST}}$)

- Block diagram of PF2/$\overline{\text{RST}}$



15.4.3 Port F registers

- Port F register functions

Register abbreviation	Data	Read	Read by read-modify-write (RMW) instruction	Write
PDRF	0	Pin state is “L” level.	PDRF value is “0”.	As output port, outputs “L” level.
	1	Pin state is “H” level.	PDRF value is “1”.	As output port, outputs “H” level.*
DDRF	0	Port input enabled		
	1	Port output enabled		

*: If the pin is an N-ch open drain pin, the pin state becomes Hi-Z.

- Correspondence between registers and pins for port F

	Correspondence between related register bits and pins							
Pin name	-	-	-	-	-	PF2*	PF1	PF0
PDRF	-	-	-	-	-	bit2	bit1	bit0
DDRF								

*: PF2/$\overline{\text{RST}}$ is the dedicated reset pin on MB95F632H/F633H/F634H/F636H.

15.4.4 Port F operations

- Operation as an output port
  - A pin becomes an output port if the bit in the DDRF register corresponding to that pin is set to “1”.
  - For a pin shared with other peripheral functions, disable the output of such peripheral functions.
  - When a pin is used as an output port, it outputs the value of the PDRF register to external pins.
  - If data is written to the PDRF register, the value is stored in the output latch and is output to the pin set as an output port as it is.
  - Reading the PDRF register returns the PDRF register value.

  - If data is written to the PDRG register, the value is stored in the output latch and is output to the pin set as an output port as it is.
  - Reading the PDRG register returns the PDRG register value.

- Operation as an input port
  - A pin becomes an input port if the bit in the DDRG register corresponding to that pin is set to “0”.
  - For a pin shared with other peripheral functions, disable the output of such peripheral functions.
  - If data is written to the PDRG register, the value is stored in the output latch but is not output to the pin set as an input port.
  - Reading the PDRG register returns the pin value. However, if the read-modify-write (RMW) type of instruction is used to read the PDRG register, the PDRG register value is returned.

- Operation as a peripheral function input pin
  - To set a pin as an input port, set the bit in the DDRG register corresponding to the input pin of a peripheral function to “0”.
  - Reading the PDRG register returns the pin value, regardless of whether the peripheral function uses that pin as its input pin. However, if the read-modify-write (RMW) type of instruction is used to read the PDRG register, the PDRG register value is returned.

- Operation at reset
  If the CPU is reset, all bits in the DDRG register are initialized to “0” and port input is enabled.

- Operation in stop mode and watch mode
  - If the pin state setting bit in the standby control register (STBC:SPL) is set to “1” and the device transits to stop mode or watch mode, the pin is compulsorily made to enter the high impedance state regardless of the DDRG register value. The input of that pin is locked to “L” level and blocked in order to prevent leaks due to input open.
  - If the pin state setting bit is “0”, the state of the port I/O or that of the peripheral function I/O remains unchanged and the output level is maintained.

- Operation of the pull-up register
  Setting the bit in the PULG register to “1” makes the pull-up resistor be internally connected to the pin. When the pin output is “L” level, the pull-up resistor is disconnected regardless of the value of the PULG register.

17. Pin States In Each Mode

Pin name	Normal operation	Sleep mode	Stop mode		Watch mode		On reset
			SPL=0	SPL=1	SPL=0	SPL=1	
PF0/X0	Oscillation input	Oscillation input	Hi-Z	Hi-Z	Hi-Z	Hi-Z	—
	I/O port*4	I/O port*4	- Previous state kept - Input blocked*2*4	- Hi-Z - Input blocked*2*4	- Previous state kept - Input blocked*2*4	- Hi-Z - Input blocked*2*4	- Hi-Z - Input enabled*1 (However, it does not function.)
PF1/X1	Oscillation input	Oscillation input	Hi-Z	Hi-Z	Hi-Z	Hi-Z	—
	I/O port*4	I/O port*4	- Previous state kept - Input blocked*2*4	- Hi-Z - Input blocked*2*4	- Previous state kept - Input blocked*2*4	- Hi-Z - Input blocked*2*4	- Hi-Z - Input enabled*1 (However, it does not function.)
PG1/X0A/ SNI1	Oscillation input	Oscillation input	Hi-Z	Hi-Z	Hi-Z	Hi-Z	—
	I/O port*4/ peripheral function I/O	I/O port*4/ peripheral function I/O	- Previous state kept - Input blocked*2*4	- Hi-Z (However, the setting of the pull-up control is effective.) - Input blocked*2*4	- Previous state kept - Input blocked*2*4	- Hi-Z (However, the setting of the pull-up control is effective.) - Input blocked*2*4	- Hi-Z - Input enabled*1 (However, it does not function.)
PG2/X1A/ SNI2	Oscillation input	Oscillation input	Hi-Z	Hi-Z	Hi-Z	Hi-Z	—
	I/O port*4/ peripheral function I/O	I/O port*4/ peripheral function I/O	- Previous state kept - Input blocked*2*4	- Hi-Z (However, the setting of the pull-up control is effective.) - Input blocked*2*4	- Previous state kept - Input blocked*2*4	- Hi-Z (However, the setting of the pull-up control is effective.) - Input blocked*2*4	- Hi-Z - Input enabled*1 (However, it does not function.)
PF2/$\overline{\text{RST}}$	I/O port	Reset input	Reset input	Reset input	Reset input	Reset input	Reset input*3
P60/INT08/ SDA/DTTI	I/O port/ peripheral function I/O	I/O port/ peripheral function I/O	- Previous state kept - Input blocked*2 (However, an external interrupt can be input when the external interrupt request is enabled.)	- Hi-Z - Input blocked*2 (However, an external interrupt can be input when the external interrupt request is enabled.)	- Previous state kept - Input blocked*2 (However, an external interrupt can be input when the external interrupt request is enabled.)	- Hi-Z - Input blocked*2 (However, an external interrupt can be input when the external interrupt request is enabled.)	- Hi-Z - Input enabled*1 (However, it does not function.)
P61/INT09/ SCL/TI1							
P62/TO10/ PPG00/ OPT0	I/O port/ peripheral function I/O	I/O port/ peripheral function I/O	- Previous state kept - Input blocked*2	- Hi-Z (However, the setting of the pull-up control is effective.) - Input blocked*2	- Previous state kept - Input blocked*2	- Hi-Z (However, the setting of the pull-up control is effective.) - Input blocked*2	- Hi-Z - Input enabled*1 (However, it does not function.)
P63/TO11/ PPG01/ OPT1							

18.2 Recommended Operating Conditions

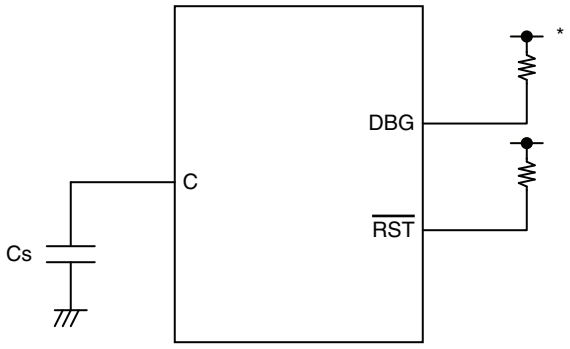
(V_{SS} = 0.0 V)

Parameter	Symbol	Value		Unit	Remarks
		Min	Max		
Power supply voltage	V_{CC}	2.4*1	5.5	V	In normal operation
		2.3	5.5		Hold condition in stop mode
Decoupling capacitor	C_S	0.022	1	µF	*2
Operating temperature	T_A	− 40	+85	°C	Other than on-chip debug mode
		+5	+35		On-chip debug mode

*1: The minimum power supply voltage becomes 2.88 V when a product with the low-voltage detection reset is used or when the on-chip debug mode is used.

*2: Use a ceramic capacitor or a capacitor with equivalent frequency characteristics. The decoupling capacitor for the V_{CC} pin must have a capacitance equal to or larger than the capacitance of C_S. For the connection to a decoupling capacitor C_S, see the diagram below. To prevent the device from unintentionally entering an unknown mode due to noise, minimize the distance between the C pin and C_S and the distance between C_S and the V_{SS} pin when designing the layout of a printed circuit board.

- DBG / $\overline{\text{RST}}$ / C pins connection diagram



*: Connect the DBG pin to an external pull-up resistor of 2 kΩ or above. After power-on, ensure that the DBG pin does not stay at “L” level until the reset output is released. The DBG pin becomes a communication pin in debug mode. Since the actual pull-up resistance depends on the tool used and the interconnection length, refer to the tool document when selecting a pull-up resistor.

WARNING: The recommended operating conditions are required in order to ensure the normal operation of the semiconductor device. All of the device's electrical characteristics are warranted when the device is operated under these conditions.

Any use of semiconductor devices will be under their recommended operating condition.
Operation under any conditions other than these conditions may adversely affect reliability of device and could result in device failure.

No warranty is made with respect to any use, operating conditions or combinations not represented on this data sheet. If you are considering application under any conditions other than listed herein, please contact sales representatives beforehand.

(V_{CC} = 5.0 V±10%, V_{SS} = 0.0 V, T_A = –40 °C to +85°C)

Parameter	Symbol	Pin name	Condition	Value			Unit	Remarks
				Min	Typ*1	Max*2		
Power supply current*3	I_V	V_{CC}	Current consumption of the comparator	—	60	160	µA	
	I_{LVD}		Current consumption of the low-voltage detection circuit	—	4	7	µA	
	I_{CRH}		Current consumption of the main CR oscillator	—	240	320	µA	
	I_{CRL}		Current consumption of the sub-CR oscillator oscillating at 100 kHz	—	7	20	µA	
	I_{NSTBY}		Current consumption difference between normal standby mode and deep standby mode T_A = +25°C	—	20	30	µA	

*1: V_{CC} = 5.0 V, T_A = +25°C

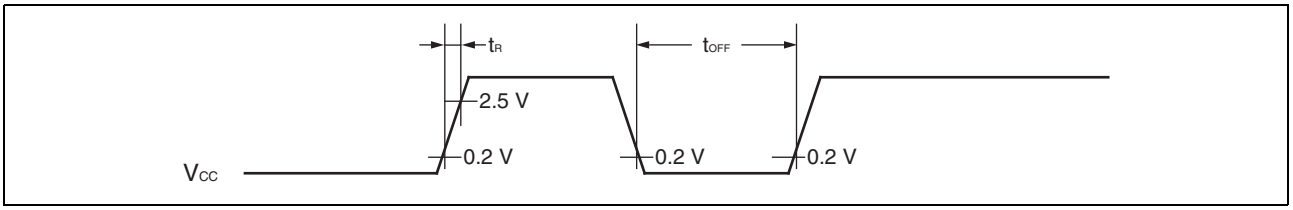
*2: V_{CC} = 5.5 V, T_A = +85°C (unless otherwise specified)

*3:
- The power supply current is determined by the external clock. When the low-voltage detection circuit is selected, the power supply current is the sum of adding the current consumption of the low-voltage detection circuit (I_{LVD}) to one of the values from I_{CC} to I_{CCH}. In addition, when both the low-voltage detection option and the CR oscillator are selected, the power supply current is the sum of adding up the current consumption of the low-voltage detection circuit (I_{LVD}), the current consumption of the CR oscillators (I_{CRH}, I_{CRL}) and a specified value. In on-chip debug mode, the CR oscillator (I_{CRH}) and the low-voltage detection circuit are always in operation, and current consumption therefore increases accordingly.
- See “4. AC Characteristics Clock Timing” for F_{CH}, F_{CL}, F_{CRH} and F_{MCRPLL}.
- See “4. AC Characteristics Source Clock/Machine Clock” for F_{MP} and F_{MPL}.
- The power supply current value in standby mode is measured in deep standby mode. The current consumption in normal standby is higher than that in deep standby mode. The power supply current value in normal standby can be found by adding the current consumption difference between normal standby mode and deep standby mode (I_{NSTBY}) to the power supply current value in deep standby mode. For details of normal standby and deep standby mode, refer to “CHAPTER 3 CLOCK CONTROLLER” in “New 8FX MB95630H Series Hardware Manual”.

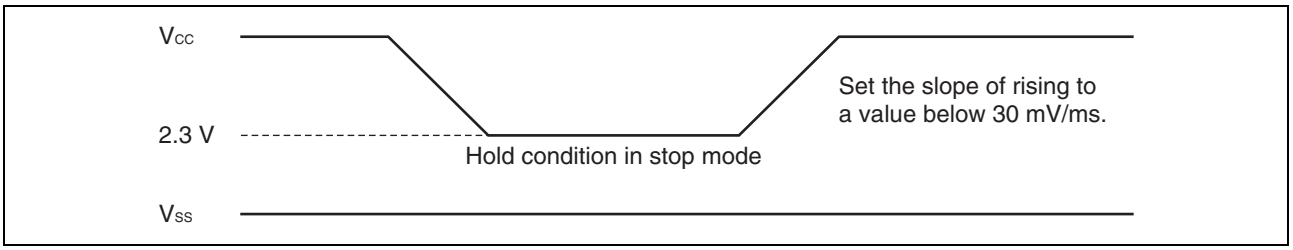
18.4.4 Power-on Reset

(V_{SS} = 0.0 V, T_A = –40°C to +85°C)

Parameter	Symbol	Condition	Value		Unit	Remarks
			Min	Max		
Power supply rising time	t_R	—	—	50	ms	
Power supply cutoff time	t_{OFF}	—	1	—	ms	Wait time until power-on



Note: A sudden change of power supply voltage may activate the power-on reset function. When changing the power supply voltage during the operation, set the slope of rising to a value below within 30 mV/ms as shown below.

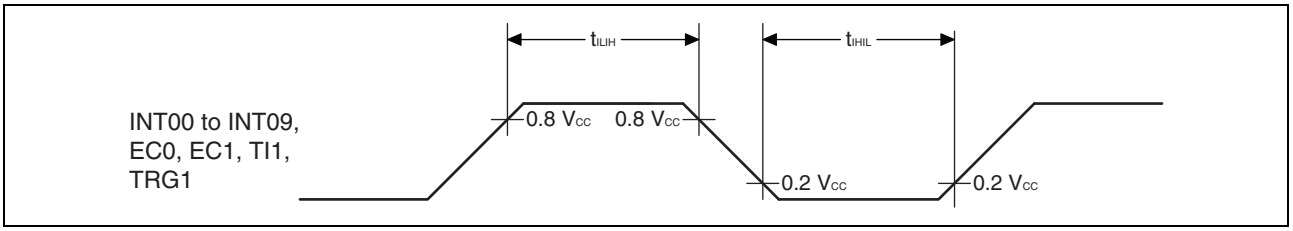


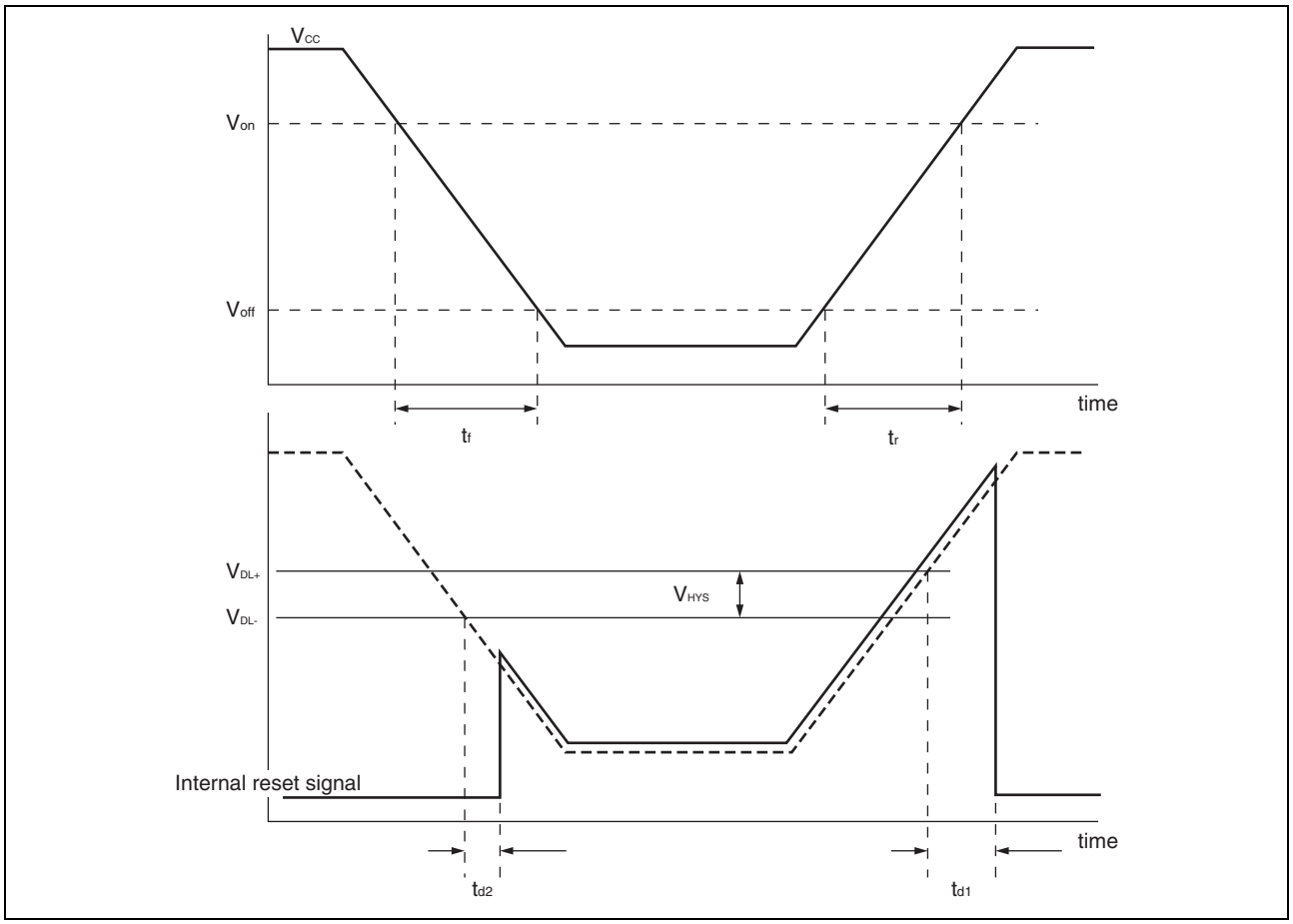
18.4.5 Peripheral Input Timing

(V_{CC} = 5.0 V±10%, V_{SS} = 0.0 V, T_A = –40°C to +85°C)

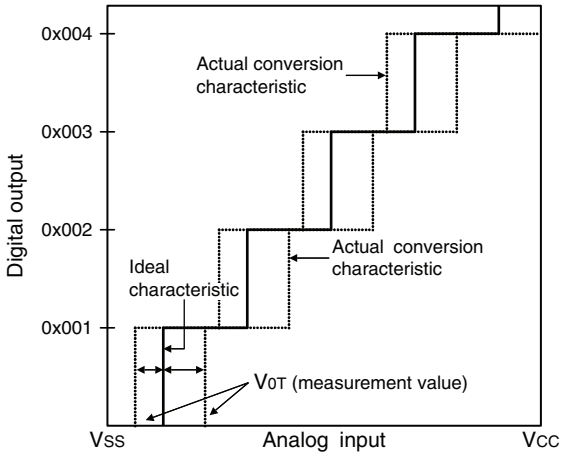
Parameter	Symbol	Pin name	Value		Unit
			Min	Max	
Peripheral input “H” pulse width	t_{ILIH}	INT00 to INT09, EC0, EC1, TI1, TRG1	2 t_{MCLK}*	—	ns
Peripheral input “L” pulse width	t_{IHIL}		2 t_{MCLK}*	—	ns

*: See “Source Clock/Machine Clock” for t_{MCLK}.

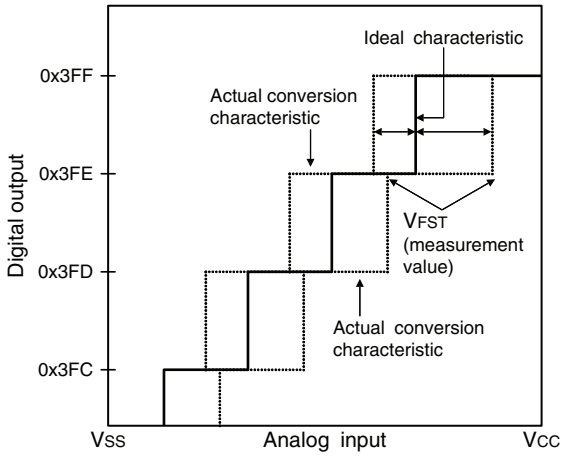



V_{CC}
V_{on}
V_{off}
time
t_f
t_r
V_{DL+}
V_{DL-}
V_{HYS}
Internal reset signal
time
t_{d2}
t_{d1}

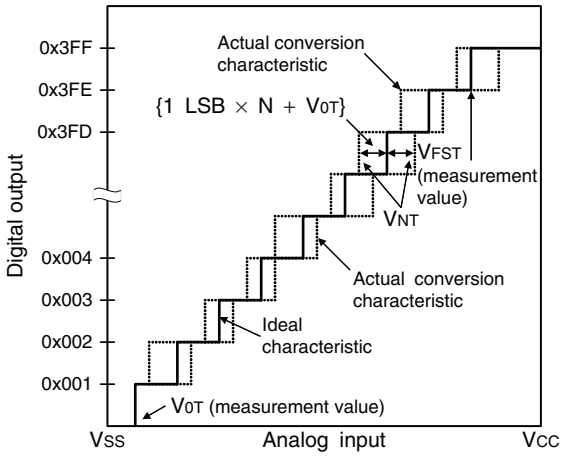
Zero transition error



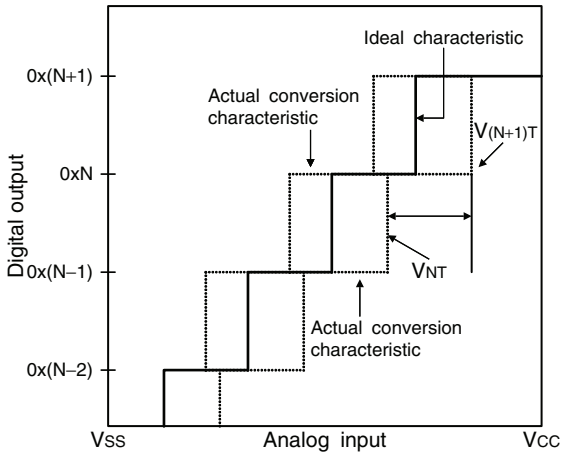
Full-scale transition error



Linearity error



Differential linearity error



$$\text{Linearity error of digital output N} = \frac{V_{NT} - \{1\ \text{LSB} \times N + V_{OT}\}}{1\ \text{LSB}}$$

$$\text{Differential linearity error of digital output N} = \frac{V_{(N+1)T} - V_{NT}}{1\ \text{LSB}} - 1$$

N : A/D converter digital output value

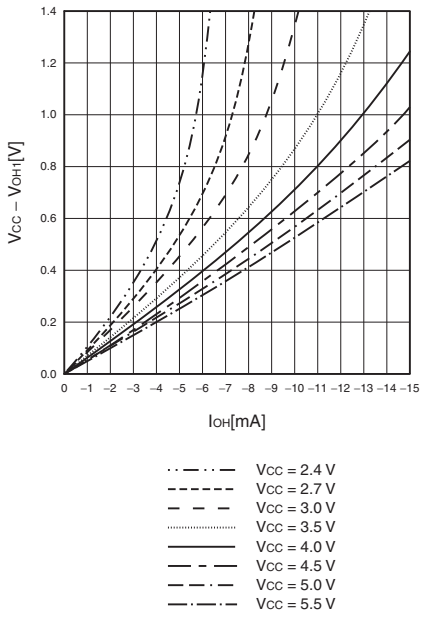
V_{NT} : Voltage at which the digital output transits from 0x(N – 1) to 0xN

V_{OT} (ideal value) = V_{SS} + 0.5 LSB [V]

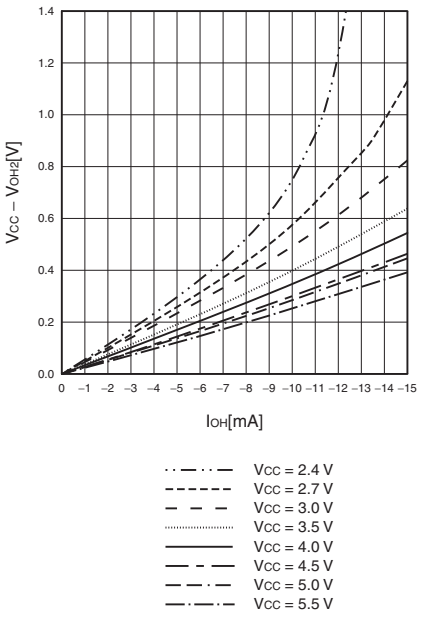
V_{FST} (ideal value) = V_{CC} – 2 LSB [V]

- Output voltage characteristics

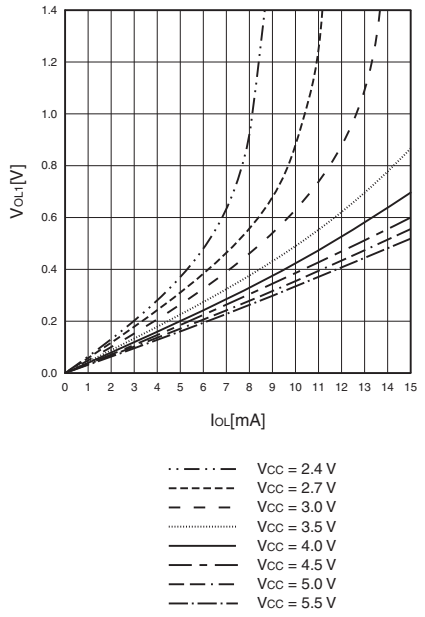
$(V_{CC} - V_{OH1}) - I_{OH}$
$T_A = +25°C$



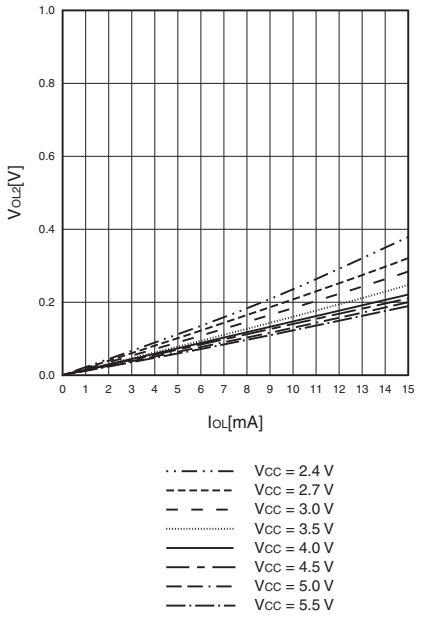
$(V_{CC} - V_{OH2}) - I_{OH}$
$T_A = +25°C$



$V_{OL1} - I_{OL}$
$T_A = +25°C$

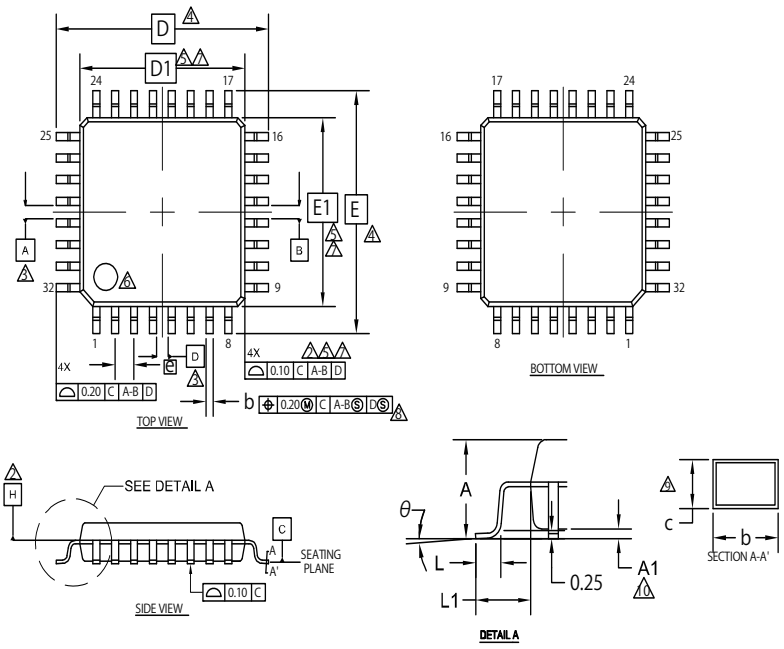


$V_{OL2} - I_{OL}$
$T_A = +25°C$



22. Package Dimension

Package Type	Package Code
LQFP 32	LQB032



SYMBOL	DIMENSIONS		
	MIN.	NOM.	MAX.
A	—	—	1.60
A1	0.05	—	0.15
b	0.32	0.35	0.43
c	0.13	—	0.18
D		9.00 BSC	
D1		7.00 BSC	
e		0.80 BSC	
E		9.00 BSC	
E1		7.00 BSC	
L	0.45	0.60	0.75
L1	0.30	0.50	0.70
θ	0°	—	8°

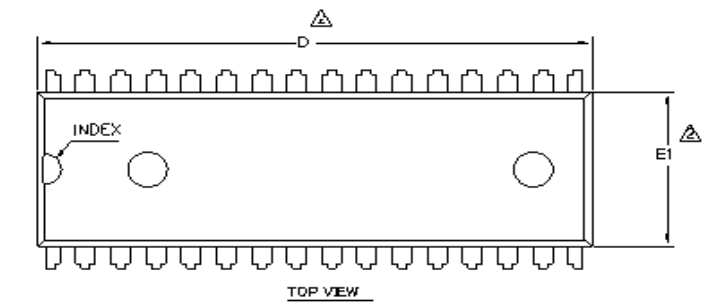
NOTES

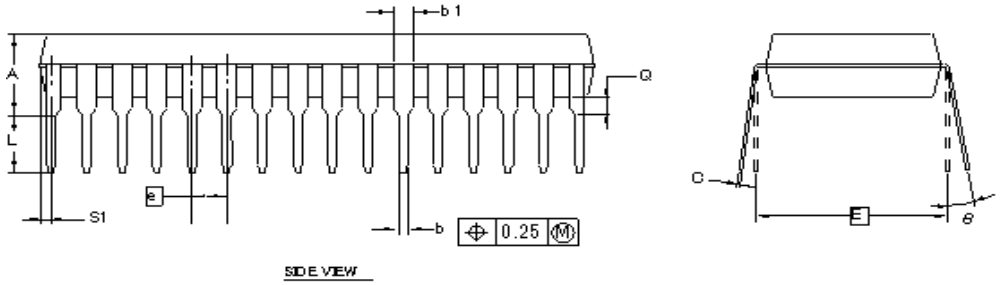
1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DATUM PLANE H IS LOCATED AT THE BOTTOM OF THE MOLD PARTING LINE COINCIDENT WITH WHERE THE LEAD EXITS THE BODY.
3. DATUMS A-B AND D TO BE DETERMINED AT DATUM PLANE H.
4. TO BE DETERMINED AT SEATING PLANE C.
5. DIMENSIONS D1 AND E1 DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE PROTRUSION IS 0.25mm PRE SIDE. DIMENSIONS D1 AND E1 INCLUDE MOLD MISMATCH AND ARE DETERMINED AT DATUM PLANE H.
6. DETAILS OF PIN 1 IDENTIFIER ARE OPTIONAL BUT MUST BE LOCATED WITHIN THE ZONE INDICATED.
7. REGARDLESS OF THE RELATIVE SIZE OF THE UPPER AND LOWER BODY SECTIONS. DIMENSIONS D1 AND E1 ARE DETERMINED AT THE LARGEST FEATURE OF THE BODY EXCLUSIVE OF MOLD FLASH AND GATE BURRS. BUT INCLUDING ANY MISMATCH BETWEEN THE UPPER AND LOWER SECTIONS OF THE MOLDER BODY.
8. DIMENSION b DOES NOT INCLUDE DAMBER PROTRUSION. THE DAMBAR PROTRUSION (S) SHALL NOT CAUSE THE LEAD WIDTH TO EXCEED b MAXIMUM BY MORE THAN 0.08mm. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE LEAD FOOT.
9. THESE DIMENSIONS APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN 0.10mm AND 0.25mm FROM THE LEAD TIP.
10. A1 IS DEFINED AS THE DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT OF THE PACKAGE BODY.

002-13879 **

PACKAGE OUTLINE, 32 LEAD LQFP
7.0X7.0X1.6 MM LQB032 REV*.*

Package Type	Package Code
SDIP 32	PDS032





SYMBOL	DIMENSIONS		
	MIN.	NOM.	MAX.
A	4.50	4.70	5.40
L	3.00	3.30	3.50
D	27.70	28.00	28.20
E	10.16 BSC		
E1	8.64	8.89	9.14
θ	0°	——	15°
c	0.20	0.27	0.30
b	0.36	0.48	0.56
b1	0.82	1.02	1.32
e	1.778 BSC		
S1	——	——	1.27
Q	0.51	——	——

NOTES
1. ALL DIMENSIONS ARE IN MILLIMETER.
2. DIMENSIONS NOT INCLUDE RESIN REMAINING.
3. TERMINAL WIDTH AND TERMINAL THICKNESS INCLUDE PLATING THICKNESS.
4. JEDEC SPECIFICATION NO. REF : N/A

PACKAGE OUTLINE, 32 LEAD PDIP
28.00X8.89X4.19 MM PDS032 REV**

002-16908 **